## Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

\* Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan



## MOS FET FK6K02010L

## FK6K02010L Silicon N-channel MOS FET

### For switching

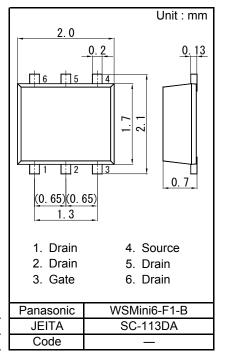
- Features
- Low drain-source On-state Resistance:RDS(on)typ. =  $13 \text{ m}\Omega$  (VGS = 4.5 V) •
- Low drive voltage: 2.5 V drive
- Halogen-free / RoHS compliant ٠ (EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)
- Marking Symbol : TA

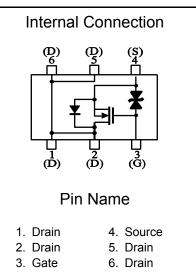
#### Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

| ■ Absolute Maximum Ratings Ta = 25       | °C     |             |      |
|--|--------|-------------|------|
| Parameter                                | Symbol | Rating      | Unit |
| Drain-source surrender voltage           | VDSS   | 20          | V    |
| Gate-source surrender voltage            | VGSS   | ±10         | V    |
| Drain current                            | ID     | 4.5         | А    |
| Peak drain current <sup>*1</sup>         | IDp    | 18          | А    |
| Power dissipation *2                     | PD     | 700         | mW   |
| Channel temperature                      | Tch    | 150         | С°   |
| Operating ambient temperature            | Topr   | -40 to +85  | °C   |
| Storage temperature                      | Tstg   | -55 to +150 | С°   |
| Note) *1 t = 10 $\mu$ s, Duty Cycle < 1% |        |             |      |

\*2 Measuring on Glass epoxy board ( $25.4 \times 25.4 \times t0.8$  mm) coated with copper foil, which has more than 300 mm<sup>2</sup> Absolute maximum rating without heat sink for PD is 150 mW.





## Panasonic

# MOS FET FK6K02010L

### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter  | Symbol   | Conditions                     | Min | Тур   | Max  | Unit |
|--|----------|--------------------------------|-----|-------|------|------|
| Drain-source surrender voltage                   | VDSS     | ID = 1 mA, VGS = 0             | 20  |       |      | V    |
| Drain-source cutoff current                      | IDSS     | VDS = 20 V, VGS = 0            |     |       | 1.0  | μA   |
| Gate-source cutoff current                       | IGSS     | VGS = ±8 V, VDS = 0            |     |       | ±10  | μA   |
| Gate threshold voltage                           | Vth      | ID = 1.0 mA, VDS = 10.0 V      | 0.4 | 0.85  | 1.3  | V    |
| Drain-source ON resistance                       | RDS(ON)1 | ID = 2.0 A, VGS = 4.5 V        |     | 13    | 17.5 | mΩ   |
|  | RDS(ON)2 | ID = 1.0 A, VGS = 2.5 V        |     | 16    | 28   |      |
| Forward transfer admittance                      | Yfs      | ID = 1.0 A, VDS =10 V          | 3.0 |       |      | S    |
| Short-circuit input capacitance (Common source)  | Ciss     |                                |     | 1 730 |      | pF   |
| Short-circuit output capacitance (Common source) | Coss     | VDS = 10 V, VGS = 0, f = 1 MHz |     | 155   |      | pF   |
| Reverse transfer capacitance (Common source)     | Crss     |                                |     | 150   |      | pF   |
| Turn-on delay time *1                            | td(on)   |                                |     | 19    |      | ns   |
| Rise time <sup>*1</sup>                          | tr       | VDD = 10 V<br>VGS = 0 to 4 V   |     | 30    |      | ns   |
| Turn-off delay time <sup>*1</sup>                | td(off)  | VGS = 0 to 4 V<br>ID=1.0A      |     | 150   |      | ns   |
| Fall time <sup>*1</sup>                          | tf       |                                |     | 75    |      | ns   |

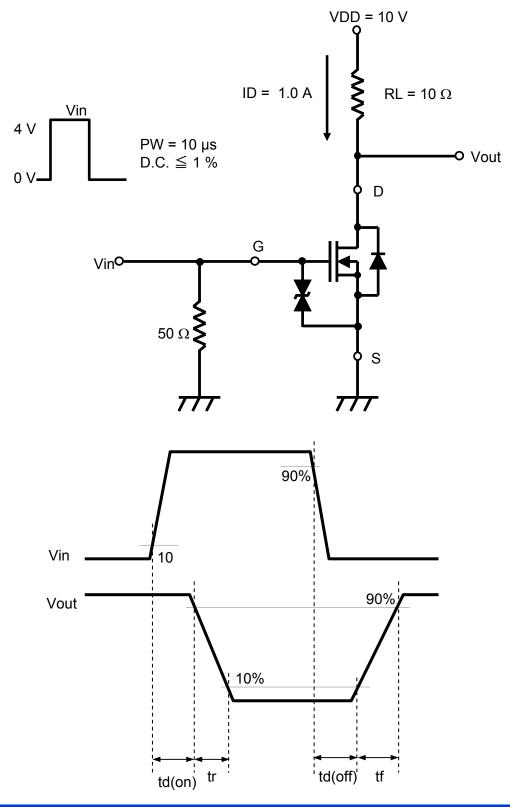
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. \*1 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time

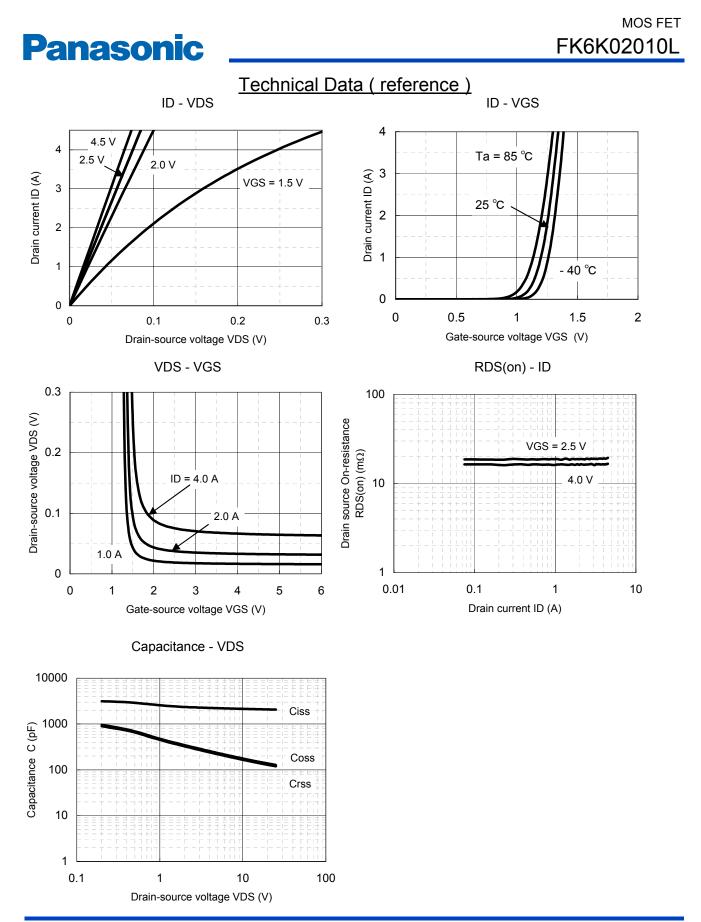
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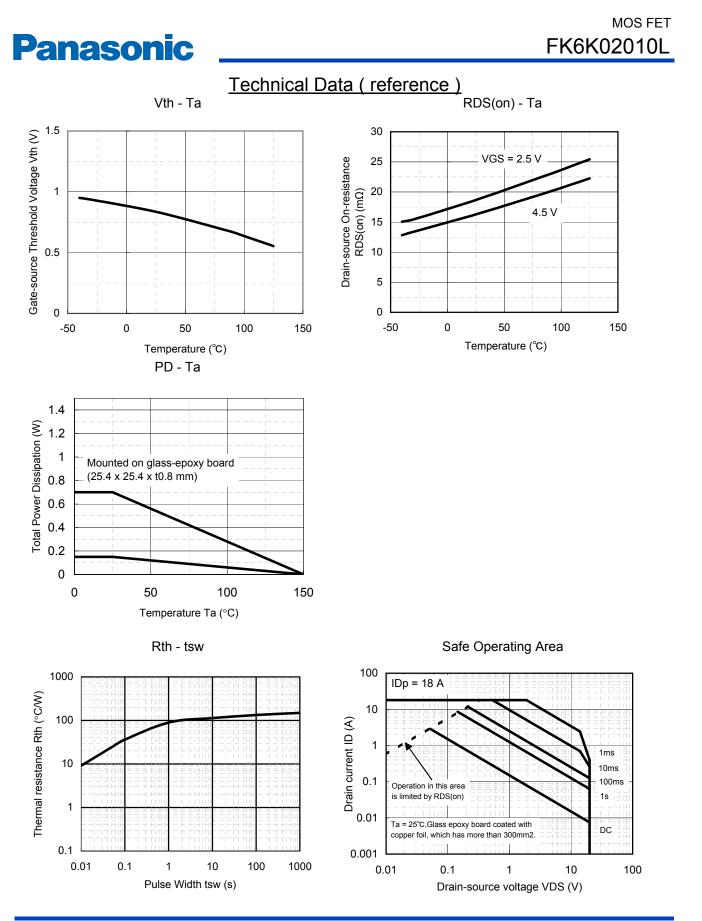


### \*1 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time

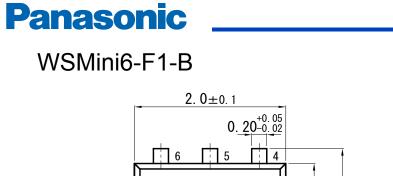


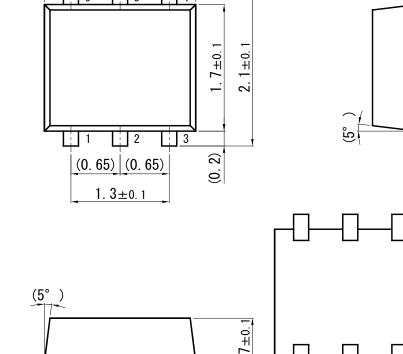
Established : 2010-06-07 Revised : 2013-07-01

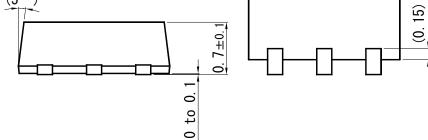




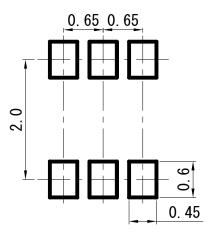
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Land Pattern (Reference) (Unit : mm)





 $0. 13 \substack{+0.05 \\ -0.03}$ 

Unit: mm

Established : 2010-06-07 Revised : 2013-07-01

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